imall

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

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High Voltage Power Transistors

DPAK for Surface Mount Applications

Designed for line operated audio output amplifier, switchmode power supply drivers and other switching applications.

Features

- Lead Formed for Surface Mount Applications in Plastic Sleeves (No Suffix)
- Electrically Similar to Popular MJE340 and MJE350
- Epoxy Meets UL 94 V-0 @ 0.125 in
- NJV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC–Q101 Qualified and PPAP Capable
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant

MAXIMUM RATINGS

Rating	Symbol	Max	Unit
Collector-Emitter Voltage	V _{CEO}	300	Vdc
Collector-Base Voltage	V _{CB}	300	Vdc
Emitter-Base Voltage	V _{EB}	3	Vdc
Collector Current – Continuous	Ι _C	0.5	Adc
Collector Current – Peak	I _{CM}	0.75	Adc
Total Power Dissipation @ T _C = 25°C Derate above 25°C	PD	15 0.12	W W/°C
Total Power Dissipation (Note 1) @ T _A = 25°C Derate above 25°C	P _D	1.56 0.012	W W/°C
Operating and Storage Junction Temperature Range	T _J , T _{stg}	-65 to +150	°C
ESD – Human Body Model MJD340 (NP MJD350 (PN		3B 2	V
ESD – Machine Model MJD340 (NP MJD350 (PN		M4 M4	V

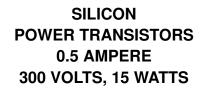
Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

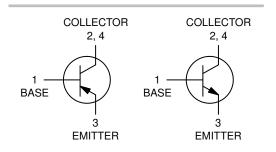
1. These ratings are applicable when surface mounted on the minimum pad sizes recommended.



ON Semiconductor®

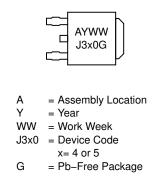
www.onsemi.com







MARKING DIAGRAM



ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 5 of this data sheet.

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Thermal Resistance, Junction-to-Case	$R_{ ext{ heta}JC}$	8.33	°C/W
Thermal Resistance, Junction-to-Ambient (Note 2)	$R_{\theta JA}$	80	°C/W
Leading Temperature for Soldering Purpose	ΤL	260	°C

2. These ratings are applicable when surface mounted on the minimum pad sizes recommended.

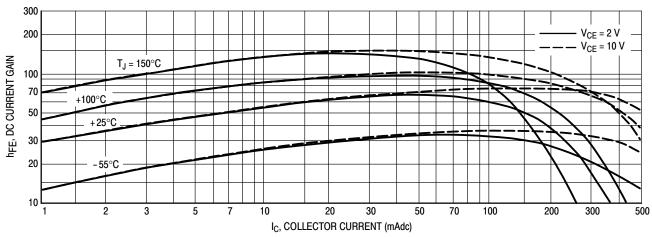
ELECTRICAL CHARACTERISTICS (T_C = 25°C unless otherwise noted)

Characteristic	Symbol	Min	Max	Unit
OFF CHARACTERISTICS	· · ·			
Collector-Emitter Sustaining Voltage (Note 3) $(I_C = 1 \text{ mA}, I_B = 0)$	V _{CEO(sus)}	300	-	V
Collector Cutoff Current $(V_{CB} = 300 \text{ V}, I_E = 0)$	ICEO	_	0.1	mA
Emitter Cutoff Current ($V_{BE} = 3 V, I_C = 0$)	I _{EBO}	_	0.1	mA
ON CHARACTERISTICS (Note 3)	· · · · ·		·	
DC Current Gain ($I_C = 50 \text{ mA}, V_{CE} = 10 \text{ V}$)	h _{FE}	30	240	-
Collector–Emitter Saturation Voltage $(I_{C} = 100 \text{ mA}, I_{B} = 10 \text{ mA})$	V _{CE(sat)}	_	1	V
Base-Emitter On Voltage (I _C = 1 A, V _{CE} = 10 V)	V _{BE(on)}	_	1.5	V
DYNAMIC CHARACTERISTICS				
Current Gain – Bandwidth Product	f _T			MHz

 $(I_{C} = 50 \text{ mA}, V_{CE} = 10 \text{ V}, f = 10 \text{ MHz})$ 10 _ Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.
Pulse Test: Pulse Width ≤ 300 µs, Duty Cycle ≤ 2%.

TYPICAL CHARACTERISTICS

MJD340





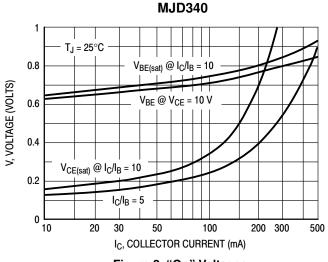
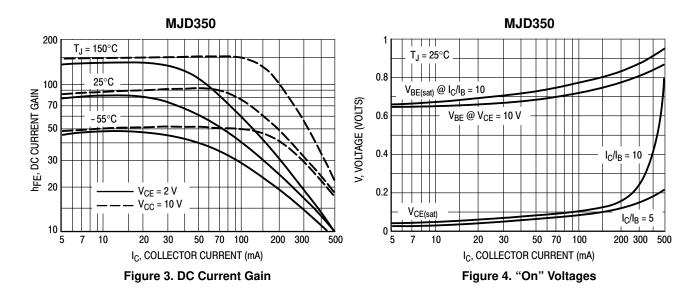


Figure 2. "On" Voltages



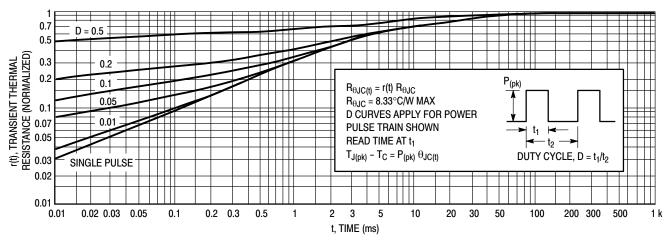


Figure 5. Thermal Response

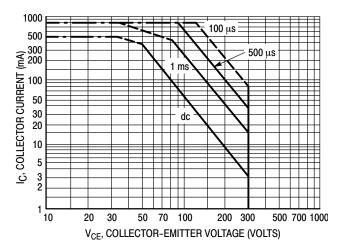


Figure 6. Active Region Safe Operating Area

There are two limitations on the power handling ability of a transistor: average junction temperature and second breakdown. Safe operating area curves indicate $I_C - V_{CE}$ limits of the transistor that must be observed for reliable operation; i.e., the transistor must not be subjected to greater dissipation than the curves indicate.

The data of Figure 6 is based on $T_{J(pk)} = 150^{\circ}$ C; T_{C} is variable depending on conditions. Second breakdown pulse limits are valid for duty cycles to 10% provided $T_{J(pk)} \le 150^{\circ}$ C. $T_{J(pk)}$ may be calculated from the data in Figure 5. At high case temperatures, thermal limitations will reduce the power that can be handled to values less than the limitations imposed by second breakdown.

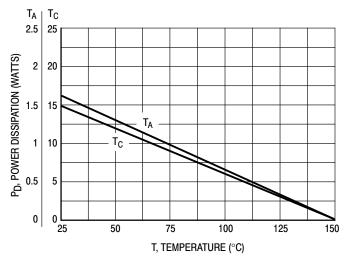


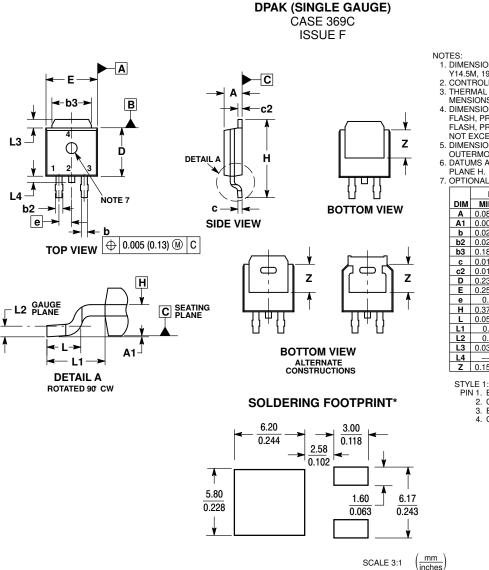
Figure 7. Power Derating

ORDERING INFORMATION

Device	Package	Shipping [†]	
MJD340G	DPAK (Pb–Free)	75 Units / Rail	
MJD340RLG	DPAK (Pb–Free)	1,800 / Tape & Reel	
MJD340T4G	DPAK (Pb-Free)	2,500 / Tape & Reel	
NJVMJD340T4G	DPAK (Pb-Free)	2,500 / Tape & Reel	
MJD350G	DPAK (Pb-Free)	75 Units / Rail	
MJD350T4G	DPAK (Pb-Free)	2,500 / Tape & Reel	
NJVMJD350T4G	DPAK (Pb–Free)	2,500 / Tape & Reel	

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

PACKAGE DIMENSIONS



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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Phone: 421 33 790 2910 Japan Customer Focus Center Phone: 81-3-5817-1050

ON Semiconductor Website: www.onsemi.com

Order Literature: http://www.onsemi.com/orderlit

For additional information, please contact your local Sales Representative

- Y14.5M, 1994. CONTROLLING DIMENSION: INCHES. THERMAL PAD CONTOUR OPTIONAL WITHIN DI-MENSIONS b3, L3 and Z.
- DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL
- NOT EXCEED 0.006 INCHES PER SIDE. 5. DIMENSIONS D AND E ARE DETERMINED AT THE
- OUTERMOST EXTREMES OF THE PLASTIC BODY. 6. DATUMS A AND B ARE DETERMINED AT DATUM
- PLANE H. OPTIONAL MOLD FEATURE

	INCHES		MILLIN	LIMETERS	
DIM	MIN	MAX	MIN	MAX	
Α	0.086	0.094	2.18	2.38	
A1	0.000	0.005	0.00	0.13	
b	0.025	0.035	0.63	0.89	
b2	0.028	0.045	0.72	1.14	
b3	0.180	0.215	4.57	5.46	
С	0.018	0.024	0.46	0.61	
c2	0.018	0.024	0.46	0.61	
D	0.235	0.245	5.97	6.22	
Е	0.250	0.265	6.35	6.73	
е	0.090 BSC		2.29 BSC		
Н	0.370	0.410	9.40	10.41	
L	0.055	0.070	1.40	1.78	
L1	0.114	14 REF 2.90 REF		REF	
L2	0.020	BSC	0.51	BSC	
L3	0.035	0.050	0.89	1.27	
L4		0.040		1.01	
Ζ	0.155		3.93		

PIN 1. BASE 2. COLLECTOR

3. 4. EMITTER COLLECTOR